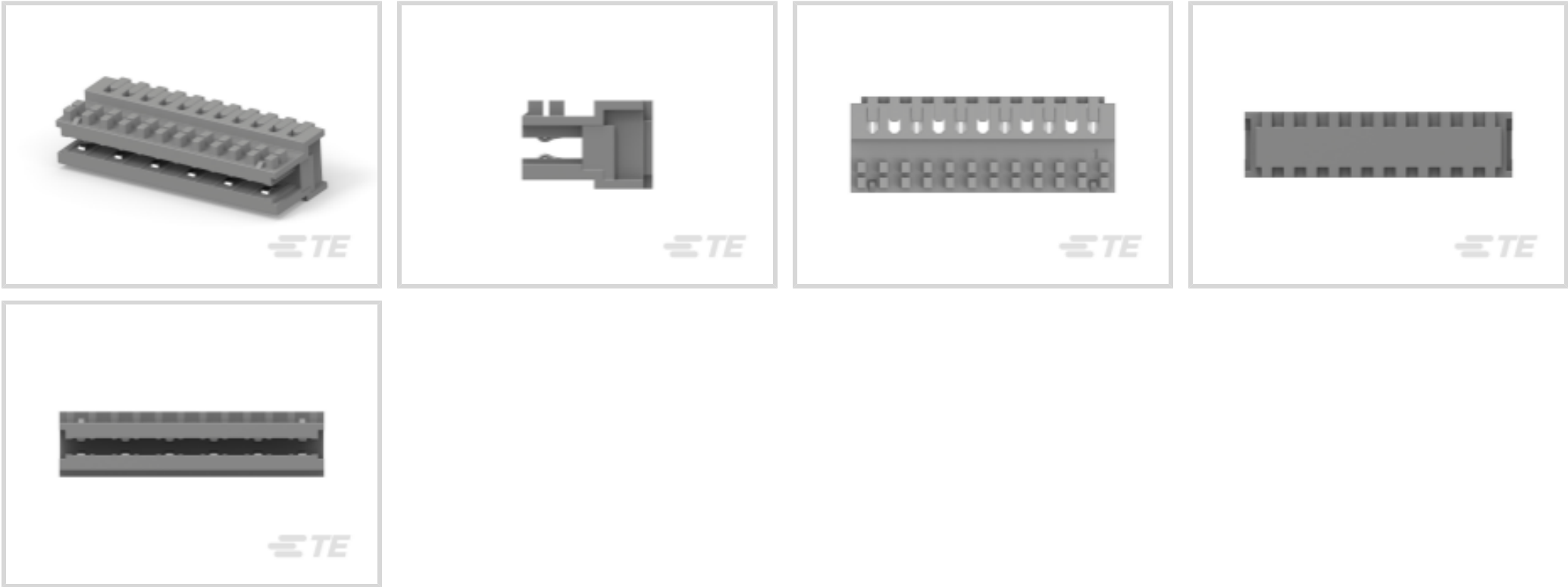




Connectors > PCB Connectors > Card Edge Connectors > Standard Edge Connectors



Connector System: **Wire-to-Board**

Number of Positions: **11**

Centerline (Pitch): **2.5 mm [ .098 in ]**

Termination Method to Wire & Cable: **Insulation Displacement (IDC)**

Number of Rows: **1**

Features

Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| Connector System                  | Wire-to-Board         |
| Connector & Housing Type          | Receptacle            |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

|                                   |                    |
|-----------------------------------|--------------------|
| Card Entry Style                  | Side               |
| Compatible With Wire & Cable Type | Discrete Wire      |
| Number of Positions               | 11                 |
| Number of Rows                    | 1                  |
| Connector Contact Load Condition  | Selectively Loaded |
| PCB Mount Orientation             | Right Angle        |

Electrical Characteristics

|                   |        |
|-------------------|--------|
| Operating Voltage | 63 VAC |
|-------------------|--------|

Body Features

|                       |      |
|-----------------------|------|
| Primary Product Color | Gray |
|-----------------------|------|

Contact Features



|                                                |            |
|------------------------------------------------|------------|
| Contact Mating Area Plating Material           | Tin (Sn)   |
| Contact Retention Within Housing               | Without    |
| Contact Base Material                          | Copper Tin |
| PCB Contact Termination Area Plating Material  | Tin        |
| Contact Type                                   | Socket     |
| Contact Mating Area Plating Material Thickness | 5 – 12 µm  |
| Contact Current Rating (Max)                   | 2 A        |

Termination Features

|                                    |                               |
|------------------------------------|-------------------------------|
| Termination Method to Wire & Cable | Insulation Displacement (IDC) |
|------------------------------------|-------------------------------|

Mechanical Attachment

|                         |                            |
|-------------------------|----------------------------|
| Mating Retention        | Without                    |
| Mating Alignment Type   | Keyed                      |
| Mating Alignment        | With                       |
| PCB Mount Alignment     | Without                    |
| Connector Mounting Type | Cable Mount (Free-Hanging) |

Housing Features

|                             |                 |
|-----------------------------|-----------------|
| Housing Entry Configuration | Both Ends Open  |
| Centerline (Pitch)          | 2.5 mm[.098 in] |
| Housing Material            | PBT             |

Dimensions

|                                      |                              |
|--------------------------------------|------------------------------|
| Card Slot Depth                      | 5 mm[.2 in]                  |
| PCB Thickness (Recommended)          | 1.5 mm[.059 in]              |
| Compatible Insulation Diameter Range | 1.2 – 1.4 mm[.047 – .055 in] |
| Connector Height                     | 7.35 mm[.29 in]              |
| Wire Size                            | 24 – 22 AWG                  |

Operation/Application

|                     |        |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Packaging Features

|                    |      |
|--------------------|------|
| Packaging Quantity | 1680 |
|--------------------|------|

Product Compliance

For compliance documentation, visit the product page on TE.com>

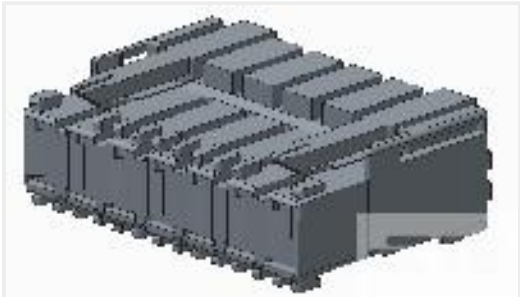


|                                               |                                                                                                                                |
|-----------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                      |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                      |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                        |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JAN 2025 (247)<br>Candidate List Declared Against: JUNE 2022 (224)<br>Does not contain REACH SVHC |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.                                                                                 |
| Solder Process Capability                     | Not applicable for solder process capability                                                                                   |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



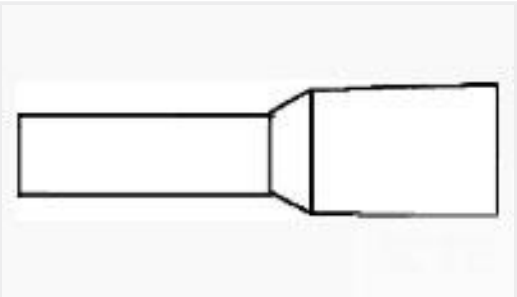
TE Part #1-1534072-7  
AMP MF MK II ASS'Y/AR 7POS



TE Part #42639-1  
RING TERMINAL 14-12 AWG BR



TE Part #6-1241961-2  
STD TIM HOUSING MKII 2POS



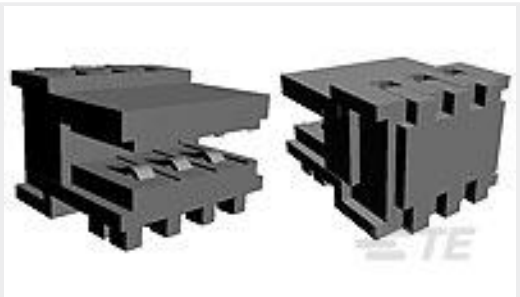
TE Part #1241004-1  
ADERENDH2,5M BLAU



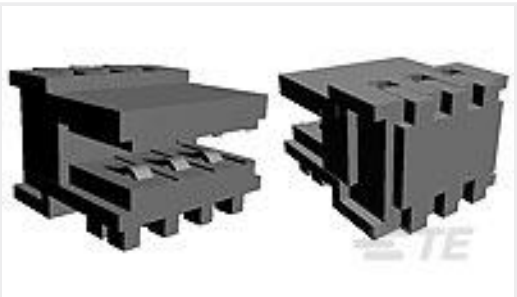
TE Part #1-1971921-7  
4/7P,RAST 2.5 Tab Header,Ex- Locking, THV



TE Part #2205062-2  
CA MICRO-MATCH MOW-MOW 8POS



TE Part #3-966480-3  
DUOPLUG2,5BUST16X3P



TE Part #3-966480-5  
DUOPLUG2,5BUST11X5P





TE Part #284865-4  
Direct mount card edge conn.,



TE Part #4-1415538-1  
RT334730WG

Documents

CAD Files

Customer View Model

ENG\_CVM\_3-966481-1\_C2.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_3-966481-1\_C2.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_3-966481-1\_C2.3d\_stp.zip

English

3D PDF

English

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_3-966481-1\_D.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_3-966481-1\_D.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_3-966481-1\_D.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

RAST Connector System Catalog

English

Product Specifications

Application Specification

English

Agency Approvals

Agency Approval Document

English

